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April 1<sup>st</sup>, 2010  
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# SuperH™ Family E10A-USB Emulator

Additional Document for User's Manual  
Supplementary Information on Using the  
SH7670, SH7671, SH7672, and SH7673

Renesas Microcomputer Development  
Environment System

SuperH™ Family

E10A-USB for SH7673 HS7673KCU01HE



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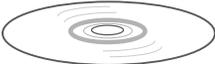


# Section 1 Connecting the Emulator with the User System

## 1.1 Components of the Emulator

The E10A-USB emulator supports the SH7670, SH7671, SH7672, and SH7673. Table 1.1 lists the components of the emulator.

**Table 1.1 Components of the Emulator**

Classification	Component	Appearance	Quantity	Remarks
Hardware	Emulator box		1	HS0005KCU01H: Depth: 65.0 mm, Width: 97.0 mm, Height: 20.0 mm, Mass: 72.9 g or HS0005KCU02H: Depth: 65.0 mm, Width: 97.0 mm, Height: 20.0 mm, Mass: 73.7 g
	User system interface cable		1	14-pin type: Length: 20 cm, Mass: 33.1 g
	User system interface cable		1	36-pin type: Length: 20 cm, Mass: 49.2 g (only for HS0005KCU02H)
	USB cable		1	Length: 150 cm, Mass: 50.6 g
Software	E10A-USB emulator setup program, SuperH™ Family E10A-USB Emulator User's Manual, Supplementary Information on Using the SH7670, SH7671, SH7672, and SH7673*, and Test program manual for HS0005KCU01H and HS0005KCU02H		1	HS0005KCU01SR, HS0005KCU01HJ, HS0005KCU01HE,  HS7652KCU01HJ, HS7652KCU01HE,  HS0005TM01HJ, and HS0005TM01HE (provided on a CD-R)

Note: Additional document for the MCUs supported by the emulator is included. Check the target MCU and refer to its additional document.

## 1.2 Connecting the Emulator with the User System

To connect the E10A-USB emulator (hereinafter referred to as the emulator), the H-UDI port connector must be installed on the user system to connect the user system interface cable. When designing the user system, refer to the recommended circuit between the H-UDI port connector and the MCU. In addition, read the E10A-USB emulator user's manual and hardware manual for the related device.

**Table 1.2 Type Number and Connector Type**

Type Number	Connector	AUD Function
HS0005KCU02H	14-pin connector	Available

## 1.3 Installing the H-UDI Port Connector on the User System

Table 1.3 shows the recommended H-UDI port connectors for the emulator.

**Table 1.3 Recommended H-UDI Port Connectors**

Connector	Type Number	Manufacturer	Specifications
14-pin connector	7614-6002	Minnesota Mining and Manufacturing Ltd.	14-pin straight type

Note: Do not place any components within 3 mm of the H-UDI port connector.

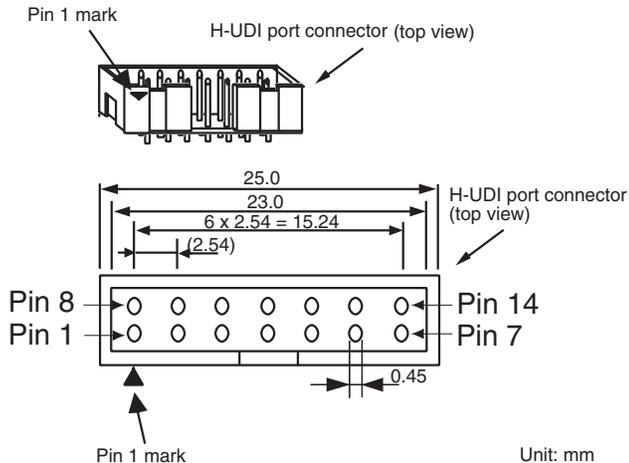
## 1.4 Pin Assignments of the H-UDI Port Connector

Figure 1.1 shows the pin assignments of the H-UDI port connector.

Note: Note that the pin number assignments of the H-UDI port connector shown on the following pages differ from those of the connector manufacturer.

Pin No.	Signal		Input/ Output*1	SH7670 SH7671 SH7672 SH7673 Pin No.	Note
1	TCK		Input	V17	
2	TRST#	*2	Input	Y18	
3	TDO		Output	W19	
4	ASEBRKAK#	*2	Input/ output	T20	
	/ ASEBRK#				
5	TMS		Input	Y19	
6	TDI		Input	V18	
7	RES#	*2	Output	W18	User reset
8	N.C.		—		
9	(GND)	*4	—		
11	UVCC		Output		
10, 12, and 13	GND		—		
14	GND	*3	Output		

- Notes:
1. Input to or output from the user system.
  2. The symbol (#) means that the signal is active-low.
  3. The emulator monitors the GND signal of the user system and detects whether or not the user system is connected.
  4. When the user system interface cable is connected to this pin and the ASEMD# pin is set to 0, do not connect to GND but to the ASEMD# pin directly.



**Figure 1.1 Pin Assignments of the H-UDI Port Connector (14 Pins)**

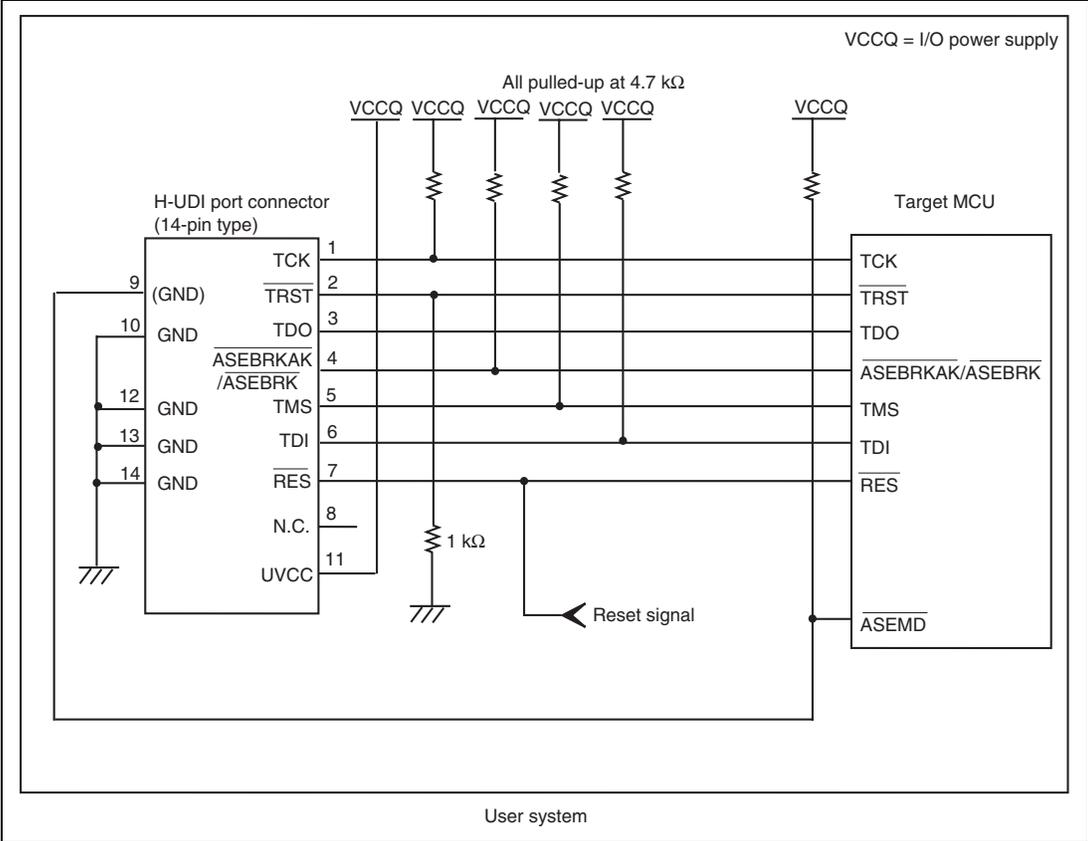
## 1.5 Recommended Circuit between the H-UDI Port Connector and the MCU

### 1.5.1 Recommended Circuit (14-Pin Type)

Figure 1.2 shows a recommended circuit for connection between the H-UDI port connector (14 pins) and the MCU when the emulator is in use.

- Notes:
1. Do not connect anything to the N.C. pins of the H-UDI port connector.
  2. The ASEMD# pin must be 0 when the emulator is connected and 1 when the emulator is not connected, respectively.
    - (1) When the emulator is used: ASEMD# = 0
    - (2) When the emulator is not used: ASEMD# = 1Figure 1.2 shows an example of circuits that allow the ASEMD# pin to be GND (0) whenever the emulator is connected by using the user system interface cable. When the ASEMD# pin is changed by switches, etc., ground pin 9. Do not connect this pin to the ASEMD# pin.
  3. When a network resistance is used for pull-up, it may be affected by a noise. Separate TCK from other resistances.
  4. The pattern between the H-UDI port connector and the MCU must be as short as possible. Do not connect the signal lines to other components on the board.
  5. Since the H-UDI of the MCU operates with the VCCQ, supply only the VCCQ to the UVCC pin. Make the emulator's switch settings so that the user power will be supplied (SW2 = 1 and SW3 = 1).
  6. The resistance value shown in figure 1.2 is for reference.
  7. The TRST# pin must be at the low level for a certain period when the power is supplied whether the H-UDI is used or not.
  8. For the pin processing in cases where the emulator is not used, refer to the hardware manual of the related MCU.

When the circuit is connected as shown in figure 1.2, the switches of the emulator are set as SW2 = 1 and SW3 = 1. For details, refer to section 3.8, Setting the DIP Switches, in the SuperH™ Family E10A-USB Emulator User’s Manual.



**Figure 1.2 Recommended Circuit for Connection between the H-UDI Port Connector and MCU when the Emulator is in Use (14-Pin Type)**



## Section 2 Software Specifications when Using the SH7670, SH7671, SH7672, and SH7673

### 2.1 Differences between the MCU and the Emulator

1. When the emulator system is initiated, it initializes the general registers and part of the control registers as shown in table 2.1. The initial values of the MCU are undefined. When the emulator is initiated from the workspace, a value to be entered is saved in a session.

**Table 2.1 Register Initial Values at Emulator Link Up**

<b>Register</b>	<b>Emulator at Link Up</b>
R0 to R14	H'00000000
R15 (SP)	Value of the SP in the power-on reset vector table
PC	Value of the PC in the power-on reset vector table
SR	H'000000F0
GBR	H'00000000
VBR	H'00000000
TBR	H'00000000
MACH	H'00000000
MACL	H'00000000
PR	H'00000000
FPSCR*	H'00040001
FPUL*	H'00000000
FPR0-15*	H'00000000

Note: If the MCU does not incorporate the floating-point unit (FPU), these registers are not displayed.

Note: When a value of the interrupt mask bit in the SR register is changed in the [Registers] window, it is actually reflected in that register immediately before execution of the user program is started. It also applies when the value is changed by the REGISTER\_SET command.

2. The emulator uses the H-UDI; do not access the H-UDI.

### 3. Low-Power States

- When the emulator is used, the sleep state can be cleared with either the clearing function or with the [STOP] button, and a break will occur.
- The memory must not be accessed or modified in software standby state.
- The memory must not be accessed or modified in deep standby state.
- Do not stop inputting the clock to the H-UDI module by using the module standby function.

### 4. Reset Signals

The MCU reset signals are only valid during emulation started with clicking the GO or STEP-type button. If these signals are enabled on the user system in command input wait state, they are not sent to the MCU.

Note: Do not break the user program when the RES#, BREQ#, or WAIT# signal is being low. A TIMEOUT error will occur. If the BREQ# or WAIT# signal is fixed to low during break, a TIMEOUT error will occur at memory access.

### 5. Direct Memory Access Controller (DMAC)

The DMAC operates even when the emulator is used. When a data transfer request is generated, the DMAC executes DMA transfer.

### 6. Memory Access during User Program Execution

During execution of the user program, memory is accessed by the following two methods, as shown in table 2.2; each method offers advantages and disadvantages.

**Table 2.2 Memory Access during User Program Execution**

<b>Method</b>	<b>Advantage</b>	<b>Disadvantage</b>
H-UDI read/write	The stopping time of the user program is short because memory is accessed by the dedicated bus master.	Cache access is disabled. Actual memory is always accessed by the H-UDI read or write.
Short break	Cache access is enabled.	The stopping time of the user program is long because the user program temporarily breaks.

Note: Accessing memory to cache control registers 1 and 2 is fixed as a short break during execution of the user program.

The method for accessing memory during execution of the user program is specified by using the [Configuration] dialog box.

**Table 2.3 Stopping Time by Memory Access (Reference)**

<b>Method</b>	<b>Condition</b>	<b>Stopping Time</b>
H-UDI read/write	Reading of one longword for the internal RAM	Reading: Maximum three bus clocks (B $\phi$ )
	Writing of one longword for the internal RAM	Writing: Maximum two bus clocks (B $\phi$ )
Short break	CPU clock: 160 MHz JTAG clock: 20 MHz  Reading or writing of one longword for the external area	About 50 ms

#### 7. Memory Access to the External Flash Memory Area

The emulator can download the load module to the external flash memory area (for details, refer to section 6.22, Download Function to the Flash Memory Area, in the SuperH™ Family E10A-USB Emulator User's Manual). Other memory write operations are enabled for the RAM area. Therefore, an operation such as memory write or BREAKPOINT should be set only for the RAM area.

## 8. Operation while Cache is Enabled

When cache is enabled, the emulator operates as shown in table 2.4.

**Table 2.4 Operation while Cache is Enabled**

<b>Function</b>	<b>Operation</b>	<b>Notes</b>
Memory write	Searches for whether or not the address to be written hits the instruction and operand caches. <ul style="list-style-type: none"><li>• When the address hits, the corresponding position of the data array is changed by the data to be written and single write is performed to the external area.</li><li>• When the address does not hit, the cache contents are not changed and single write is performed to the external area.</li></ul>	<ul style="list-style-type: none"><li>• The contents of the address array are not changed before or after writing of memory.</li></ul>
Memory read	Searches for whether or not the address to be read hits the operand cache. <ul style="list-style-type: none"><li>• When the address hits, the corresponding position of the data array is read.</li><li>• When the address does not hit, single write is performed to the external area.</li></ul>	<ul style="list-style-type: none"><li>• The instruction cache is not searched for.</li><li>• The contents of the address array are not changed before or after reading of memory.</li></ul>
BREAKPOINT	Clears the V and LRU bits of all entries in the instruction cache to 0 if a BREAKPOINT is set or canceled.  Clears the V and LRU bits of all entries in the instruction cache to 0 if a break occurs when a BREAKPOINT has been set.	<ul style="list-style-type: none"><li>• Use the Event Condition if you do not wish to change the contents of the instruction cache.</li></ul>
Program load	Writes the contents of the data cache to the external memory and clears the V and LRU bits of entries in the instruction and data caches to 0 after loading of the program has been completed.	

If memory is read from or written to the disabled cache area, cache is not searched for but the external area is accessed.

## 9. Using WDT

The WDT does not operate during break.

## 10. Loading Sessions

Information in [JTAG clock] of the [Configuration] dialog box cannot be recovered by loading sessions. Thus the TCK value will be as follows:

- When HS0005KCU01H or HS0005KCU02H is used: TCK = 10.00 MHz

## 11. [IO] Window

- Display and modification

There are two registers to be separately used for write and read operations.

**Table 2.5 Register with Different Access Size**

Register Name	Usage	Register
WTCSR(W)	Write	Watchdog timer control/status register
WTCNT(W)	Write	Watchdog timer counter
WTCSR(R)	Read	Watchdog timer control/status register
WTCNT(R)	Read	Watchdog timer counter
WRCSR(W)	Write	Watchdog reset control/status register
WRCSR(R)	Read	Watchdog reset control/status register

- Customization of the I/O-register definition file

The internal I/O registers can be accessed from the [IO] window. However, note the following when accessing the SDMR register of the bus-state controller. Before accessing the SDMR register, specify addresses to be accessed in the I/O-register definition file (SH7670.IO, SH7671.IO, SH7672.IO and SH7673.IO) and then activate the High-performance Embedded Workshop. After the I/O-register definition file is created, the MCU's specifications may be changed. If each I/O register in the I/O-register definition file differs from addresses described in the hardware manual, change the I/O-register definition file according to the description in the hardware manual. The I/O-register definition file can be customized depending on its format. However, the emulator does not support the bit-field function.

- Verify

In the [IO] window, the verify function of the input value is disabled.

## 12. Illegal Instructions

Do not execute illegal instructions with STEP-type commands.

## 13. Reset Input

During execution of the user program, the emulator may not operate correctly if a contention occurs between the following operations for the emulator and the reset input to the target device:

- Setting an Event Condition
- Setting an internal trace
- Displaying the content acquired by an internal trace
- Reading or writing of a memory

Note that those operations should not contend with the reset input to the target device.

## 14. Contention between the Change of the FRQCR Register and the Debugging Functions

The following notes are required for the user program for changing the multiplication rate of PLL circuit 1 to change the frequency:

- Avoid contention between the change of the FRQCR register in the user program and the memory access from the [Memory] window, etc.
- When the automatic updating function is used in the [Monitor] window or [Watch] window, generate and set a break of Event Condition for an instruction immediately before changing the FRQCR register. Contention will be avoided by generating a break and executing the user program again.

For the change of the multiplication rate of PLL circuit 1 and the FRQCR register, refer to the hardware manual for the MCU.

## 2.2 Specific Functions for the Emulator when Using the SH7670, SH7671, SH7672, and SH7673

### 2.2.1 Event Condition Functions

The emulator is used to set event conditions for the following three functions:

- Break of the user program
- Internal trace
- Start or end of performance measurement

Table 2.6 lists the types of Event Condition.

**Table 2.6 Types of Event Condition**

<b>Event Condition Type</b>	<b>Description</b>
Address bus condition (Address)	Sets a condition when the address bus (data access) value or the program counter value (before or after execution of instructions) is matched.
Data bus condition (Data)	Sets a condition when the data bus value is matched. Byte, word, or longword can be specified as the access data size.
Bus state condition (Bus State)	There are two bus state condition settings: Bus state condition: Sets a condition when the data bus value is matched. Read/Write condition: Sets a condition when the read/write condition is matched.
Count	Sets a condition when the specified other conditions are satisfied for the specified counts.
Reset point	A reset point is set when the count and the sequential condition are specified.
Action	Selects the operation when a condition (such as a break, a trace halt condition, or a trace acquisition condition) is matched.

Using the [Combination action (Sequential or PtoP)] dialog box, which is opened by selecting [Combination action (Sequential or PtoP)] from the pop-up menu on the [Event Condition] sheet, specifies the sequential condition and the start or end of performance measurement.

Table 2.7 lists the combinations of conditions that can be set under Ch1 to Ch11 and the software trace.

**Table 2.7 Dialog Boxes for Setting Event Conditions**

Dialog Box		Function				Action
		Address Bus Condition (Address)	Data Bus Condition (Data)	Bus State Condition (Bus Status)	Count Condition (Count)	
[Event Condition 1]	Ch1	O	O	O	O	O (B, T1, and P)
[Event Condition 2]	Ch2	O	O	O	X	O (B, T1, and P)
[Event Condition 3]	Ch3	O	X	X	X	O (B and T2)
[Event Condition 4]	Ch4	O	X	X	X	O (B and T3)
[Event Condition 5]	Ch5	O	X	X	X	O (B and T3)
[Event Condition 6]	Ch6	O	X	X	X	O (B and T2)
[Event Condition 7]	Ch7	O	X	X	X	O (B and T2)
[Event Condition 8]	Ch8	O	X	X	X	O (B and T2)
[Event Condition 9]	Ch9	O	X	X	X	O (B and T2)
[Event Condition 10]	Ch10	O	X	X	X	O (B and T2)
[Event Condition 11]	Ch11	O (reset point)	X	X	X	O (B and T2)

Notes: 1. O: Can be set in the dialog box.  
X: Cannot be set in the dialog box.

2. For the Action item,

B: Setting a break is enabled.

T1: Setting the trace halt and acquisition conditions are enabled for the internal trace.

T2: Setting the trace halt is enabled for the internal trace.

T3: Setting the trace halt and point-to-point is enabled for the internal trace.

P: Setting a performance-measurement start or end condition is enabled.

The [Event Condition 11] dialog box is used to specify the count of [Event Condition 1] and becomes a reset point when the sequential condition is specified.

**Sequential Setting:** Using the [Combination action (Sequential or PtoP)] dialog box specifies the sequential condition and the start or end of performance measurement.

**Table 2.8 Conditions to Be Set**

<b>Classification</b>	<b>Item</b>	<b>Description</b>
[Ch1, 2, 3] list box		Sets the sequential condition and the start or end of performance measurement using Event Conditions 1 to 3 and 11.
	Don't care	Sets no sequential condition or the start or end of performance measurement.
	Break: Ch3-2-1	Breaks when a condition is satisfied in the order of Event Condition 3, 2, 1.
	Break: Ch3-2-1, Reset point	Breaks when a condition is satisfied in the order of Event Condition 3, 2, 1. Enables the reset point of Event Condition 11.
	Break: Ch2-1	Breaks when a condition is satisfied in the order of Event Condition 2, 1.
	Break: Ch2-1, Reset point	Breaks when a condition is satisfied in the order of Event Condition 2, 1. Enables the reset point.
	I-Trace stop: Ch3-2-1	Halts acquisition of an internal trace when a condition is satisfied in the order of Event Condition 3, 2, 1.
	I-Trace stop: Ch3-2-1, Reset point	Halts acquisition of an internal trace when a condition is satisfied in the order of Event Condition 3, 2, 1. Enables the reset point.
	I-Trace stop: Ch2-1	Halts acquisition of an internal trace when a condition is satisfied in the order of Event Condition 2, 1.
	I-Trace stop: Ch2-1, Reset point	Halts acquisition of an internal trace when a condition is satisfied in the order of Event Condition 2, 1. Enables the reset point.
	Ch2 to Ch1 PA	Sets the performance measurement period during the time from the satisfaction of the condition set in Event Condition 2 (start condition) to the satisfaction of the condition set in Event Condition 1 (end condition).

**Table 2.8 Conditions to Be Set (cont)**

<b>Classification</b>	<b>Item</b>	<b>Description</b>
[Ch1, 2, 3] list box (cont)	Ch1 to Ch2 PA	Sets the performance measurement period during the time from the satisfaction of the condition set in Event Condition 1 (start condition) to the satisfaction of the condition set in Event Condition 2 (end condition).
[Ch4, 5] list box	Sets the point-to-point of the internal trace (the start or end condition of trace acquisition) using Event Conditions 4 and 5.	
	Don't care	Sets no start or end condition of trace acquisition.
	I-Trace: Ch5 to Ch4 PtoP	Sets the acquisition period during the time from the satisfaction of the condition set in Event Condition 5 (start condition) to the satisfaction of the condition set in Event Condition 4 (end condition).
	I-Trace: Ch5 to Ch4 PtoP, power-on reset	Sets the acquisition period during the time from the satisfaction of the condition set in Event Condition 5 (start condition) to the satisfaction of the condition set in Event Condition 4 (end condition) or the power-on reset.

- Notes:
1. After the sequential condition and the count specification condition of Event Condition 1 have been set, break and trace acquisition will be halted if the sequential condition is satisfied for the specified count.
  2. If a reset point is satisfied, the satisfaction of the condition set in Event Condition will be disabled. For example, if the condition is satisfied in the order of Event Condition 3, 2, reset point, 1, the break or trace acquisition will not be halted. If the condition is satisfied in the order of Event Condition 3, 2, reset point, 3, 2, 1, the break and trace acquisition will be halted.
  3. If the start condition is satisfied after the end condition has been satisfied by measuring performance, performance measurement will be restarted. For the measurement result after a break, the measurement results during performance measurement are added.
  4. If the start condition is satisfied after the end condition has been satisfied by the point-to-point of the internal trace, trace acquisition will be restarted.

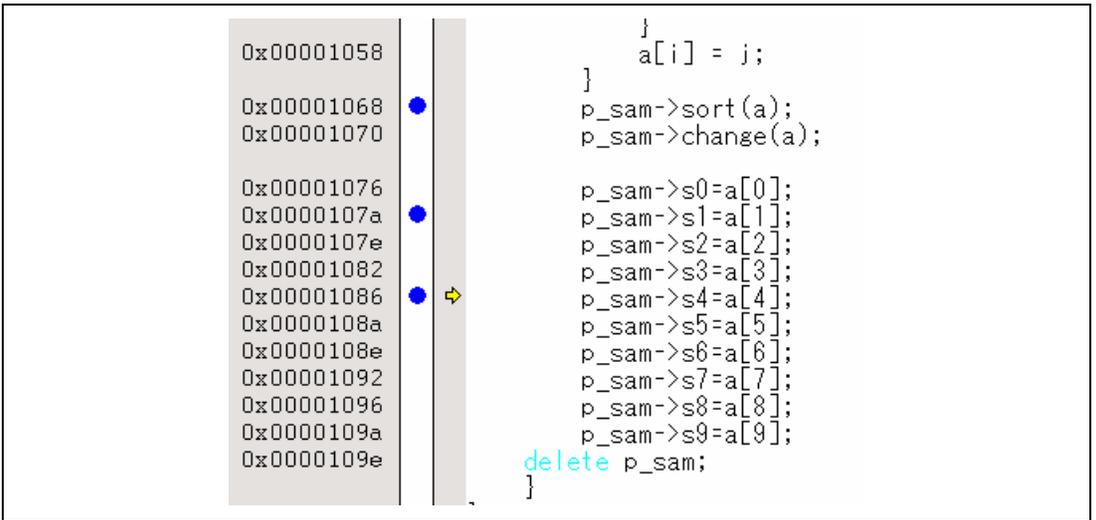
**Usage Example of Sequential Break Extension Setting:** A tutorial program provided for the product is used as an example. For the tutorial program, refer to section 6, Tutorial, in the SuperH™ Family E10A-USB Emulator User's Manual.

The conditions of Event Condition are set as follows:

1. Ch3  
Breaks address H'00001068 when the condition [Only program fetched address after] is satisfied.
2. Ch2  
Breaks address H'0000107a when the condition [Only program fetched address after] is satisfied.
3. Ch1  
Breaks address H'00001086 when the condition [Only program fetched address after] is satisfied.  
Note: Do not set other channels.
4. Sets the content of the [Ch1,2,3] list box to [Break: Ch 3-2-1] in the [Combination action (Sequential or PtoP)] dialog box.
5. Enables the condition of Event Condition 1 from the popup menu by clicking the right mouse button on the [Event Condition] sheet.

Then, set the program counter and stack pointer (PC = H'00000800, R15 = H'00010000) in the [Registers] window and click the [Go] button. If this does not execute normally, issue a reset and execute the above procedures.

The program is executed up to the condition of Ch1 and halted. Here, the condition is satisfied in the order of Ch3 -> 2 -> 1.



**Figure 2.1 [Source] Window at Execution Halted (Sequential Break)**

If the sequential condition, performance measurement start/end, or point-to-point for the internal trace is set, conditions of Event Condition to be used will be disabled. Such conditions must be enabled from the popup menu by clicking the right mouse button on the [Event Condition] sheet.

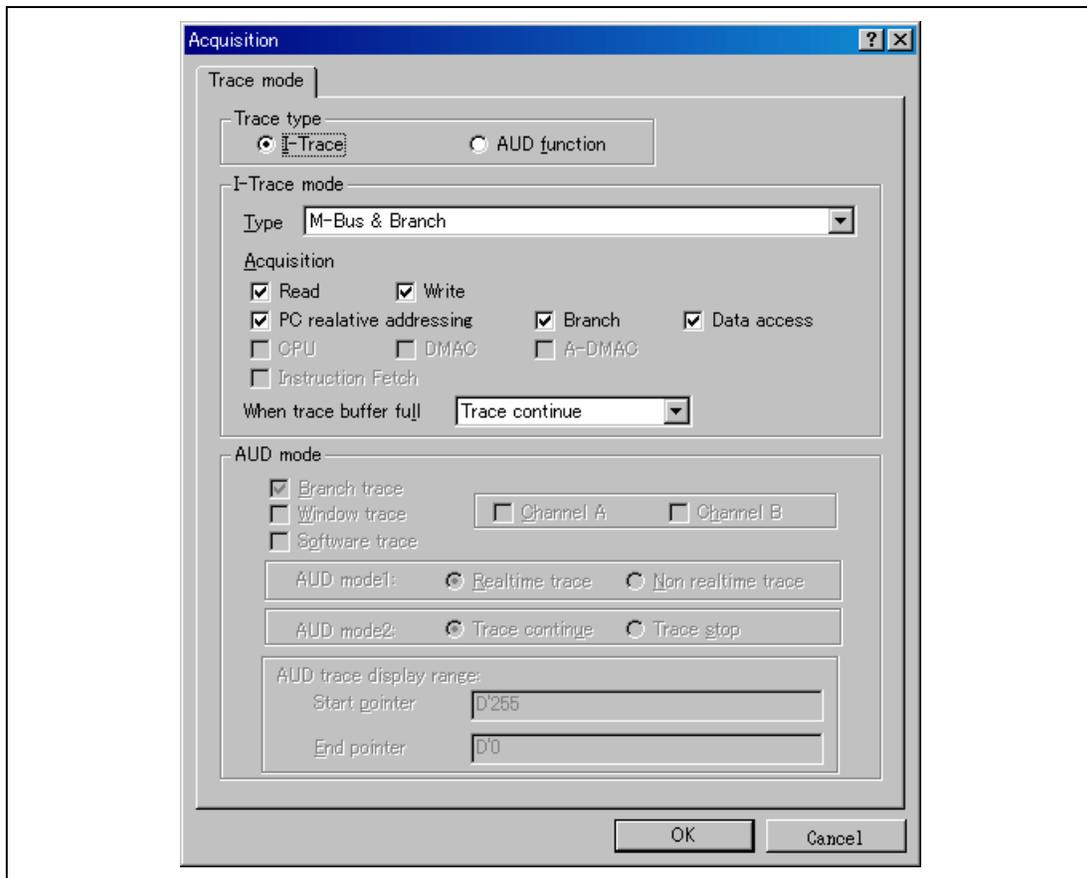
- Notes:
1. If the Event condition is set for the slot in the delayed branch instruction by the program counter (after execution of the instruction), the condition is satisfied before executing the instruction in the branch destination (when a break has been set, it occurs before executing the instruction in the branch destination).
  2. Do not set the Event condition for the SLEEP instruction by the program counter (after execution of the instruction).
  3. When the Event condition is set for the 32-bit instruction by the program counter, set that condition in the upper 16 bits of the instruction.
  4. If the power-on reset and the Event condition are matched simultaneously, no condition will be satisfied.
  5. Do not set the Event condition for the DIVU or DIVS instruction by the program counter (after execution of the instruction).
  6. If a condition of which intervals are satisfied closely is set, no sequential condition will be satisfied.
    - Set the Event conditions, which are satisfied closely, by the program counter with intervals of two or more instructions.
    - After the Event condition has been matched by accessing data, set the Event condition by the program counter with intervals of 17 or more instructions.

7. If the settings of the Event condition or the sequential conditions are changed during execution of the program, execution will be suspended. (The number of clocks to be suspended during execution of the program is a maximum of about 102 bus clocks (B $\phi$ ). If the bus clock (B $\phi$ ) is 66.6 MHz, the program will be suspended for 1.53  $\mu$ s.)
8. If the settings of Event conditions or the sequential conditions are changed during execution of the program, the emulator temporarily disables all Event conditions to change the settings. During this period, no Event condition will be satisfied.
9. If the break condition before executing an instruction is set to the instruction followed by DIVU and DIVS, the factor for halting a break will be incorrect under the following condition:  
If a break occurs during execution of the above DIVU and DIVS instructions, the break condition before executing an instruction, which has been set to the next instruction, may be displayed as the factor for halting a break.
10. If the break conditions before and after executing instructions are set to the same address, the factor for halting a break will be incorrectly displayed. The factor for halting a break due to the break condition after executing an instruction will be displayed even if a break is halted by the break condition before executing an instruction.
11. Do not set the break condition after executing instructions and BREAKPOINT (software break) to the same address.
12. When the emulator is being connected, the user break controller (UBC) function is not available.

### 2.2.2 Trace Functions

The emulator supports the internal trace function. The AUD trace is not available for this MCU. The internal traces are set in the [Acquisition] dialog box of the [Trace] window.

**Internal Trace Function:** When [I-Trace] is selected for [Trace type] on the [Trace Mode] page of the [Acquisition] dialog box, the internal trace can be used.



**Figure 2.2 [Acquisition] Dialog Box – Internal Trace Function**

The following three items can be selected as the internal trace from [Type] of [I-Trace mode].

**Table 2.9 Information on Acquiring the Internal Trace**

Item	Acquisition Information
[M-Bus & Branch]	Acquires the data and branch information on the M-bus. <ul style="list-style-type: none"> <li>• Data access (read/write)</li> <li>• PC-relative access</li> <li>• Branch information</li> </ul>
[I-Bus]	Acquires the data on the I-bus. <ul style="list-style-type: none"> <li>• Data access (read/write)</li> <li>• Selection of the bus master on the I-bus (CPU/DMA/A-DMA)</li> <li>• Instruction fetch</li> </ul>
[I-Bus, M-Bus & Branch]	Acquires the contents of [M-Bus & Branch] and [I-Bus].

After selecting [Type] of [I-Trace mode], select the content to be acquired from [Acquisition]. Typical examples are described below (note that items disabled for [Acquisition] are not acquired).

- Example of acquiring branch information only:  
Select [M-Bus & Branch] from [Type] and enable [Branch] on [Acquisition].
- Example of acquiring the read or write access (M-bus) only by a user program:  
Select [M-Bus & Branch] from [Type] and enable [Read], [Write], and [Data access] on [Acquisition].
- Example of acquiring the read access only by DMA (I-bus):  
Select [I-Bus] from [Type] and enable [Read], [DMA], and [Data access] on [Acquisition].

Using Event Condition restricts the condition; the following three items are set as the internal trace conditions.

**Table 2.10 Trace Conditions of the Internal Trace**

Item	Acquisition Information
Trace halt	Acquires the internal trace until the Event Condition is satisfied. (The trace content is displayed in the [Trace] window after a trace has been halted. No break occurs in the user program.)
Trace acquisition	Acquires only the data access where the Event Condition is satisfied.
Point-to-point	Traces the period from the satisfaction of Event Condition 4 to the satisfaction of Event Condition 5.

To restrict trace acquisition to access for only a specific address or specific function of a program, an Event Condition can be used. Typical examples are described below.

- Example of halting a trace with a write access (M-bus) to H'FFF80000 by the user program as a condition (trace halt):

Set the condition to be acquired on [I-Trace mode].

Set the following in the [Event Condition 1] or [Event Condition 2] dialog box:

Address condition: Set [Address] and H'FFF80000.

Bus state condition: Set [M-Bus] and [Write].

Action condition: Disable [Acquire Break] and set [Acquire Trace] for [Stop].

- Example of acquiring the write access (M-bus) only to H'FFF80000 by the user program (trace acquisition condition):

Select [M-Bus & Branch] from [Type] and enable [Write] and [Data access] on [Acquisition].

Set the following in the [Event Condition 1] or [Event Condition 2] dialog box:

Address condition: Set [Address] and H'FFF80000.

Bus state condition: Set [M-Bus] and [Write].

Action condition: Disable [Acquire Break] and set [Acquire Trace] for [Condition].

For the trace acquisition condition, the condition to be acquired by Event Condition should be acquired by [I-Trace mode].

- Example of acquiring a trace for the period while the program passes H'1000 through H'2000 (point-to-point):

Set the condition to be acquired on [I-Trace mode].

Set the address condition as H'1000 in the [Event Condition 5] dialog box.

Set the address condition as H'2000 in the [Event Condition 4] dialog box.

Set [I-Trace] as [Ch5 to Ch4 PtoP] in the [Combination action (Sequential or PtoP)] dialog box.

When point-to-point and trace acquisition condition are set simultaneously, they are ANDed.

## Notes on Internal Trace:

- **Timestamp**

The timestamp is the clock counts of B $\phi$  (48-bit counter). Table 2.11 shows the timing for acquiring the timestamp.

**Table 2.11 Timing for the Timestamp Acquisition**

Item	Acquisition Information	Counter Value Stored in the Trace Memory
M-bus data access		Counter value when data access (read or write) has been completed
Branch		Counter value when the next bus cycle has been completed after a branch
I-bus	Fetch	Counter value when a fetch has been completed
	Data access	Counter value when data access has been completed

- **Point-to-point**

The trace-start condition is satisfied when the specified instruction has been fetched. Accordingly, if the trace-start condition has been set for the overrun-fetched instruction (an instruction that is not executed although it has been fetched at a branch or transition to an interrupt), tracing is started during overrun-fetching of the instruction. However, when overrun-fetching is achieved (a branch is completed), tracing is automatically suspended. If the start and end conditions are satisfied closely, trace information will not be acquired correctly.

The execution cycle of the instruction fetched before the start condition is satisfied may be traced.

When the I-bus is acquired, do not specify point-to-point.

Memory access may not be acquired by the internal trace if it occurs at several instructions immediately before satisfaction of the point-to-point end condition.

- **Halting a trace**

Do not set the trace end condition for the sleep instruction and the branch instruction that the delay slot becomes the sleep instruction.

- Trace acquisition condition

Do not set the trace end condition for the sleep instruction and the branch instruction according to which the delay slot becomes the sleep instruction.

When [I-Bus, M-Bus & Branch] is selected and the trace acquisition condition is set for the M-bus and I-bus with Event Condition, set the M-bus condition and the I-bus condition for [Event Condition 1] and [Event Condition 2], respectively.

If the settings of [I-Trace mode] are changed during execution of the program, execution will be suspended. (The number of clocks to be suspended during execution of the program is a maximum of about 51 peripheral clocks (P $\phi$ ) + 15 bus clocks (B $\phi$ ). If the peripheral clock (P $\phi$ ) is 33.3 MHz and the bus clock (B $\phi$ ) is 66.6 MHz, the program will be suspended for 1.757  $\mu$ s.)

- Displaying a trace

If a trace is displayed during execution of the program, execution will be suspended to acquire the trace information. (The number of clocks to be suspended during execution of the program is a maximum of about 20480 peripheral clocks (P $\phi$ ) + 4096 bus clocks (B $\phi$ ). If the peripheral clock (P $\phi$ ) is 33.3 MHz and the bus clock (B $\phi$ ) is 66.6 MHz, the program will be suspended for 676.52  $\mu$ s.)

- Branch trace

If breaks occur immediately after executing non-delayed branch and TRAPA instructions and generating a branch due to exception or interrupt, a trace for one branch will not be acquired immediately before such breaks.

However, this does not affect on generation of breaks caused by a BREAKPOINT and a break before executing instructions of Event Condition.

- Writing memory immediately before generating a break

If an instruction is executed to write memory immediately before generating a break, trace acquisition may not be performed.

### 2.2.3 Notes on Using the JTAG (H-UDI) Clock (TCK)

1. Set the JTAG clock (TCK) frequency to lower than the frequency of the peripheral module clock and to 20 MHz or lower.
2. The initial value of the JTAG clock (TCK) is 10.00 MHz.
3. A value to be set for the JTAG clock (TCK) is initialized after executing [Reset CPU] or [Reset Go]. Thus the TCK value will be 10.00 MHz.

### 2.2.4 Notes on Setting the [Breakpoint] Dialog Box

1. When an odd address is set, the next lowest even address is used.
2. A BREAKPOINT is accomplished by replacing instructions of the specified address. It cannot be set to the following addresses:
  - An area other than CS and the internal RAM
  - An instruction in which Break Condition 2 is satisfied
  - A slot instruction of a delayed branch instruction
3. During step operation, specifying BREAKPOINTS and Event Condition breaks are disabled.
4. When execution resumes from the address where a BREAKPOINT is specified and a break occurs before Event Condition execution, single-step operation is performed at the address before execution resumes. Therefore, realtime operation cannot be performed.
5. When a BREAKPOINT is set to the slot instruction of a delayed branch instruction, the PC value becomes an illegal value. Accordingly, do not set a BREAKPOINT to the slot instruction of a delayed branch instruction.
6. If an address of a BREAKPOINT cannot be correctly set in the ROM or flash memory area, a mark ● will be displayed in the [BP] area of the address on the [Source] or [Disassembly] window by refreshing the [Memory] window, etc. after Go execution. However, no break will occur at this address. When the program halts with the event condition, the mark ● disappears.
7. If you wish to use a BREAKPOINT (software break), specify the SH2A\_SBSTK command to enable use of a user stack before setting a PC break. While enabled, extra four bytes of a user stack are used when a break occurs. The value of the stack pointer (R15) must be correctly set in advance because a user stack is to be used. By default, use of a user stack is disabled. For details on the command, refer to the help file.

- Example  
To enable use of a user stack:  
>SH2A\_SBSTK enable

### **2.2.5 Notes on Setting the [Event Condition] Dialog Box and the BREAKCONDITION\_SET Command**

1. When [Go to cursor], [Step In], [Step Over], or [Step Out] is selected, the settings of Event Condition 3 are disabled.
2. When an Event Condition is satisfied, emulation may stop after two or more instructions have been executed.

### **2.2.6 Performance Measurement Function**

The emulator supports the performance measurement function.

1. Setting the performance measurement conditions

To set the performance measurement conditions, use the [Performance Analysis] dialog box and the PERFORMANCE\_SET command. When any line in the [Performance Analysis] window is clicked with the right mouse button, a popup menu is displayed and the [Performance Analysis] dialog box can be displayed by selecting [Setting].

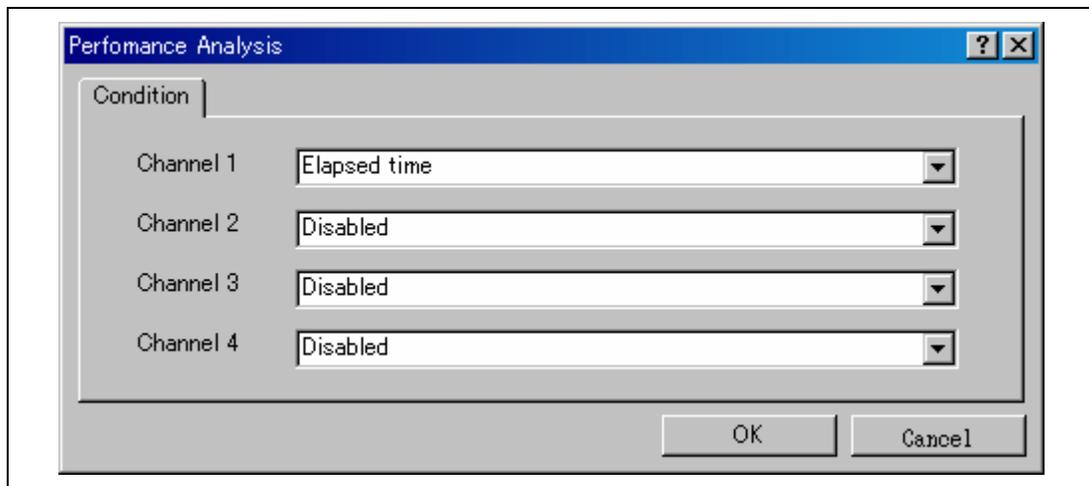
Note: For the command line syntax, refer to the online help.

(a) Specifying the measurement start/end conditions

The measurement start/end conditions are specified by using Event Condition 1,2. The [Ch1,2,3] list box of the [Combination action (Sequential or PtoP)] dialog box can be used.

**Table 2.12 Measurement Period**

Classification	Item	Description
Selection in the [Ch1, 2, 3] list box	Ch2 to Ch1 PA	The period from the satisfaction of the condition set in Event Condition 2 (start condition) to the satisfaction of the condition set in Event Condition 1 (end condition) is set as the performance measurement period.
	Ch1 to Ch2 PA	The period from the satisfaction of the condition set in Event Condition 1 (start condition) to the satisfaction of the condition set in Event Condition 2 (end condition) is set as the performance measurement period.
	Other than above	The period from the start of execution of the user program to the occurrence of a break is measured.



**Figure 2.3 [Performance Analysis] Dialog Box**

For measurement tolerance,

- The measured value includes tolerance.
- Tolerance will be generated before or after a break.

Note: When [Ch2 to Ch1 PA] or [Ch1 to Ch2 PA] is selected, to execute the user program, specify conditions set in Event Condition 2 and Event Condition 1 and one or more items for performance measurement.

(b) Measurement item

Items are measured with [Channel 1 to 4] in the [Performance Analysis] dialog box.  
Maximum four conditions can be specified at the same time.

**Table 2.13 Measurement Item**

<b>Selected Name</b>	<b>Option</b>
Disabled	None
Elapsed time	AC (The number of execution cycles ( $I\phi$ ) is set as the measurement item.)
Branch instruction counts	BT
Number of execution instructions	I
Number of execution 32bit-instructions	I32
Exception/interrupt counts	EA
Interrupt counts	INT
Data cache-miss counts	DC
Instruction cache-miss counts	IC
All area access counts	ARN
All area instruction access counts	ARIN
All area data access counts	ARND
Cacheable area access counts	CDN (data access)
Cacheable area instruction access counts	CIN
Non cacheable area data access counts	NCN
URAM area access counts	UN
URAM area instruction access counts	UIN
URAM area data access counts	UDN
Internal I/O area data access counts	IODN
Internal ROM area access counts	RN
Internal ROM area instruction access counts	RIN
Internal ROM area data access counts	RDN
All area access cycle	ARC
All area instruction access cycle	ARIC
All area data access cycle	ARDC
All area access stall	ARS
All area instruction access stall	ARIS
All area data access stall	ARDS

Note: Selected names are displayed for CONDITION in the [Performance Analysis] window.  
Options are parameters for <mode> of the PERFORMANCE\_SET command.

Note: If the internal ROM is not installed on the product, do not set the measurement item for the internal ROM area.

## 2. Displaying the measured result

The measured result is displayed in the [Performance Analysis] window or the PERFORMANCE\_ANALYSIS command with hexadecimal (32 bits).

Note: If a performance counter overflows as a result of measurement, “\*\*\*\*\*” will be displayed.

## 3. Initializing the measured result

To initialize the measured result, select [Initialize] from the popup menu in the [Performance Analysis] window or specify INIT with the PERFORMANCE\_ANALYSIS command.

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**SuperH™ Family E10A-USB Emulator  
Additional Document for User's Manual  
Supplementary Information on Using the SH7670, SH7671,  
SH7672, and SH7673**

Publication Date: Rev.1.01, August 23, 2007  
Published by: Sales Strategic Planning Div.  
Renesas Technology Corp.  
Edited by: Customer Support Department  
Global Strategic Communication Div.  
Renesas Solutions Corp.

Renesas Technology Corp. Sales Strategic Planning Div. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan

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REJ10J1706-0101